



THE UNITED STATES PATENT AND TRADEMARK OFFICE

2814

In re the Application of:

Norio FUKASAWA et al

Serial Number: 09/029,608

Group Art Unit: 2814

Filed: May 15, 1998

Examiner: Graybill, D.

For: **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE AND METHOD FOR MOUNTING THE DEVICE**

AMENDMENT TRANSMITTAL

Commissioner for Patents
Washington, D.C. 20231

July 30, 2001

Sir:

Transmitted herewith is an Amendment in the above-identified application.

The fee has been calculated as shown below:

		CLAIMS AS AMENDED						
		Claims Remaining After Amendment	Highest Number Previously Paid For		Present Extra	Small Entity	Large Entity	Additional Fee
Total Claims		42	50	=	0	X \$9	X \$18	
Independent Claims		19	17	=	2	X \$40	X \$80	160.00
# First Presentation of Multiple Dependent Claims						\$135	270	
TOTAL FEES ENCLOSED:								\$160.00

07/01/2001 MHOLDER1 00000057 09029608

150.00 0P

150.00 0P

RECEIVED
JULY 2 2001
CUSTODIAN OF CERTIFIED COPIES

- X Enclosed please find our check in the amount of **\$160.00** for the additional claims fee in connection with this amendment. The Commissioner is hereby authorized to charge payment for any additional fees associated with this communication or credit any overpayment to Deposit Account No. 01-2340. Two duplicates of this sheet are attached.

Respectfully submitted,
ARMSTRONG, WESTERMAN, HATTORI,
McLELAND & NAUGHTON, LLP



Stephen G. Adrian
Attorney for Applicants
Reg. No. 32,878

Atty. Docket No. 980233
1725 K Street, N.W., Suite 1000
Washington, DC 20006
Tel: (202) 659-2930
Fax: (202) 887-0357
SGA/rmf



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

281F
S-N-1
R. Shultz

RECEIVED
TECHNOLOGY CENTER 2800
JUL 30 2001

In re the Application of:

Norio FUKASAWA et al

Serial Number: 09/029,608

Group Art Unit: 2814

Filed: May 15, 1998

Examiner: Graybill, D.

For: **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE AND METHOD FOR MOUNTING THE DEVICE**

AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

July 30, 2001

Sir:

In response to the Office Action dated April 30, 2001, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 54-64, 70-77, 79-85 and non-elected claims 103-107 without prejudice or disclaimer.

Please add new claims 109-131 as follows:

109. A semiconductor device comprising:

a semiconductor element having a surface on which protruding electrodes are formed;
a resin layer formed on the surface of the semiconductor element so as to seal the protruding electrodes except end portions thereof; and